

Claims:

We claim:

1. A method of creating a stack of integrated circuits selectively connected to provide increased memory density in an application, the method comprising the steps of:

providing a carrier frame configured to have a plurality of members emergent into a window within the carrier frame;

applying a solder-containing compound to the first side of the members;

placing a first integrated circuit in contact with the members;

processing the combination of the first integrated circuit and the carrier frame with a heat source to create solder connections between the members and the first integrated circuit;

applying a solder-containing compound to the second side of the members of the carrier frame;

placing a second integrated circuit in contact with the members;

processing the combination of the first integrated circuit and the carrier frame with a heat source to create solder connections between the members and the second integrated circuit.

2. The method of claim 1 in which multiple iterations of the carrier frame are created in a carrier bed.

3. The method of claim 1 in which the resulting assembly of the carrier frame and the first and second integrated circuits is further processed by separation of the members from the carrier frame.

4. The method of claim 1 in which the carrier frame has indents between the body of the carrier frame and the members to simplify later separation of the carrier frame body from the members.

5. The method of claim 1 in which the first and second integrated circuits are placed in contact with the members with a pick and place tool.